

MICROSYSTEMS ENABLED PV

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OUTLINE

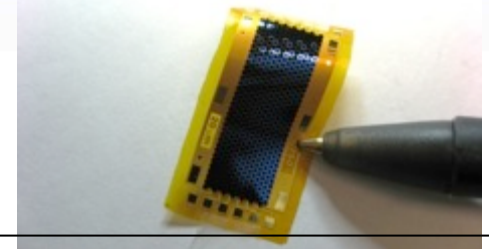
- **Technology benefits**
- Process flow/assembly examples
- Cost analysis
- From R&D to commercialization
- 3DIC/hybrid assembly and new functionality



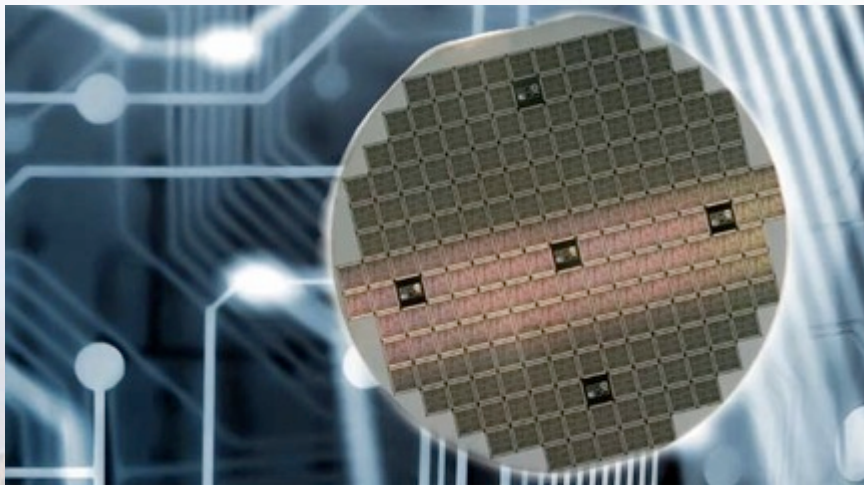
MEPV CORE COMPETITIVE ADVANTAGE

MEPV leverages concepts and technologies from existing successful microelectronics industry (IC, MEMS, LED, LCD, etc.):

- Take advantage of beneficial scaling effects
 - Improved performance
 - Reduced cost
 - New functionality
- Parallel vs. serial manufacturing
- Increased integration - system vs. cell (component) paradigm
- Utilize established manufacturing supply chain and infrastructure (reducing CapEx)



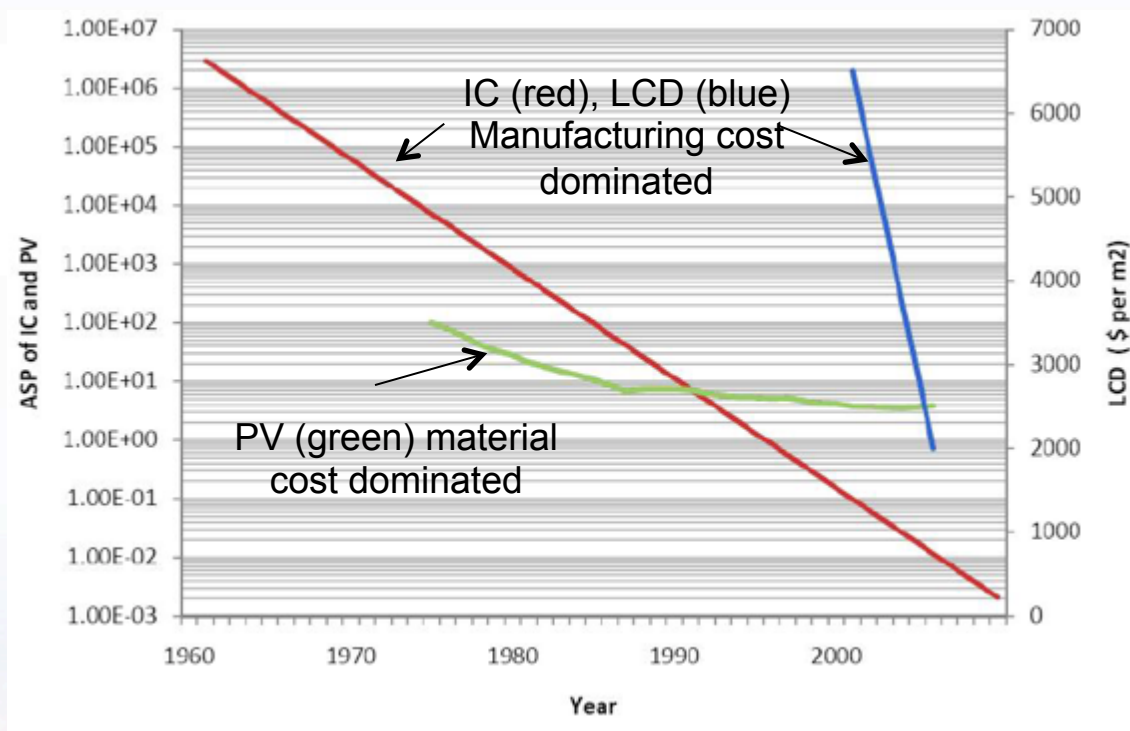
No other PV technology benefits from similar industry synergies



- Integrated Circuit Market Size: \$300B
- LCD Market Size: \$102B
- LED Market Size: \$12.5B
- MEMS Market Size: \$10B
- PV Market Size:



Potential for Cost Reduction

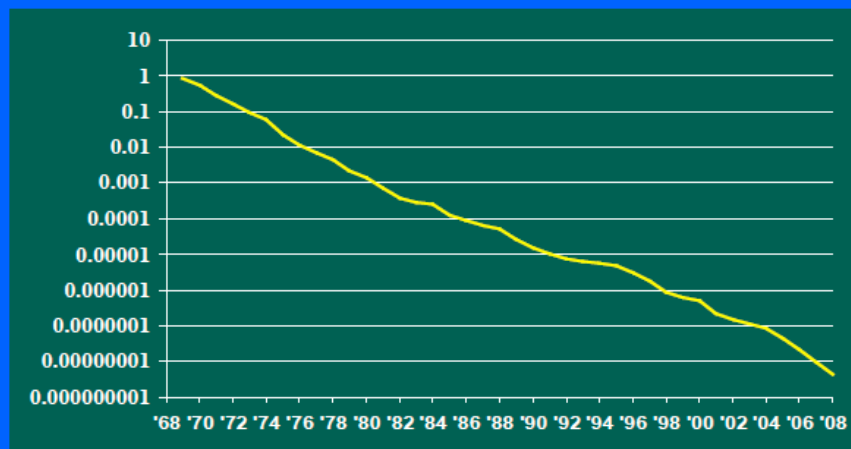


Future cost reductions are much more likely for MEPV than wafered silicon PV since manufacturing costs are a much larger component of the module costs relative to material costs. (Typically manufacturing costs are driven down more rapidly than materials costs.)



Manufacturing Tools Have Driven ~500x Price Reductions in Processed Silicon

Average Transistor Price by Year



Source: Intel/WSTS, 8/07

- In 1975, the average price per transistor was ~\$0.02 (4- μ m features).
- In 2008, the average price per transistor was ~\$5x10⁻⁹ (45 nm features)
- This is a 4,000,000x reduction in cost
 - Device scaling accounts for ~8,000x cost reduction (\$/transistor)
 - Manufacturing efficiencies account for ~500x reduction in the price of processed Silicon.

Scalability

Established Polysilicon supply (9-9s purity)

2010 >100,000 metric tons (Hemlock, Wacker,
REC, MEMC)

2011 >120,000 metric tons

2012 - OCI (S.Korea) – 62,000 metric tons
GCL Poly (China) – 65,000 metric tons
world total > 200,000 metric tons

[Bloomberg Energy Finance]

Standard Si wafered PV

~ 5-6 grams Si/W_{peak}

MEPV - < 0.1 gram Si/W_{peak}

Silane/TCS main feedstock

10x thinner cells

no kerf loss (usually 50% for standard Si PV)

>10x optical concentration



200 MW_p/year unit line

- Small IC Fab: 5,000 8" wafers/week
(@30 wfr/hr, IC industry standard = 60 wfr/hr)
- 10 pick-and-place tools: 130,000 parts/hr
- 2,900 m² PV modules produced per day
(0.7 acres)
- 200W x 2,900 = 0.58 MW_p/day

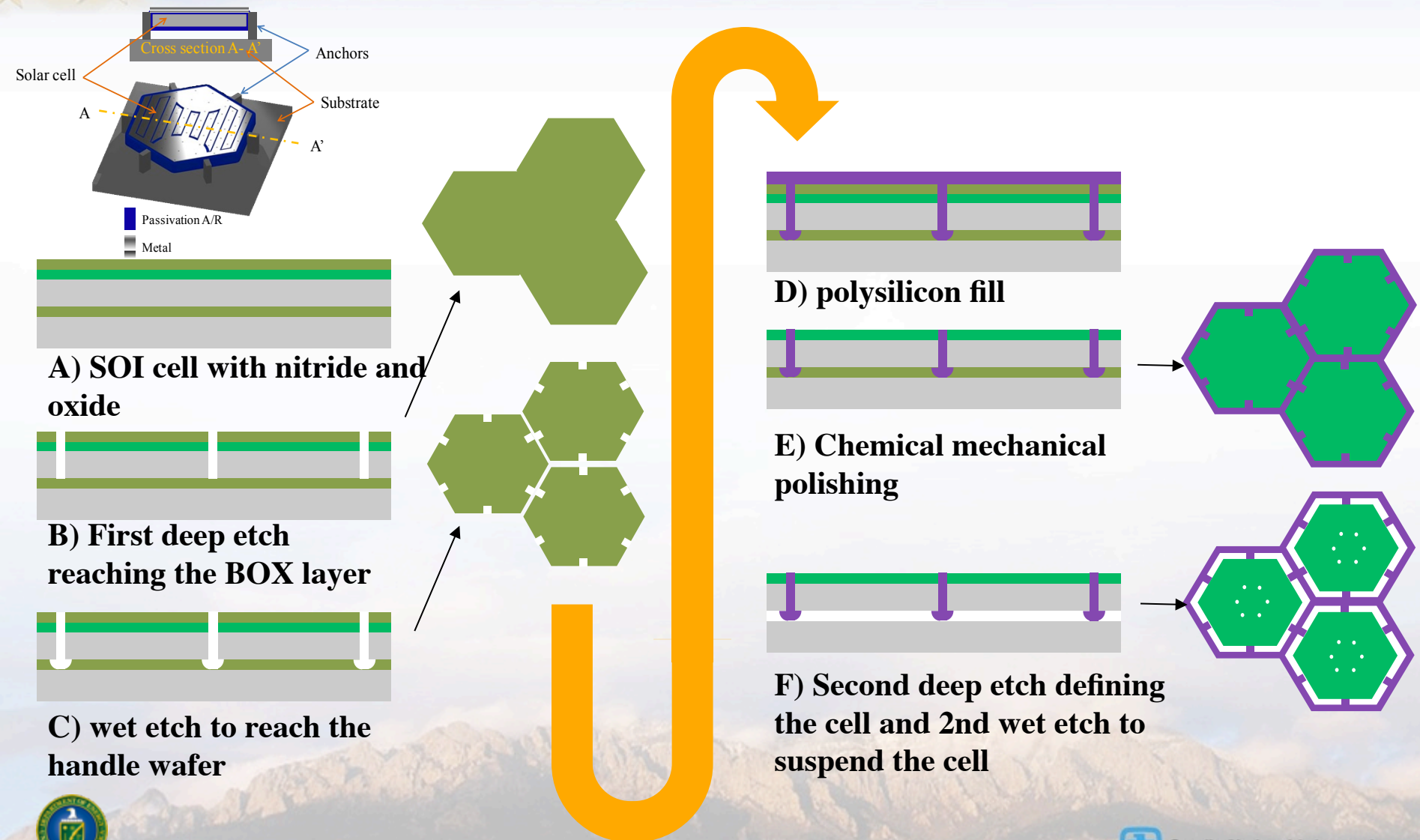
Scalability > 100GWp/year

US generation capacity ~1TW



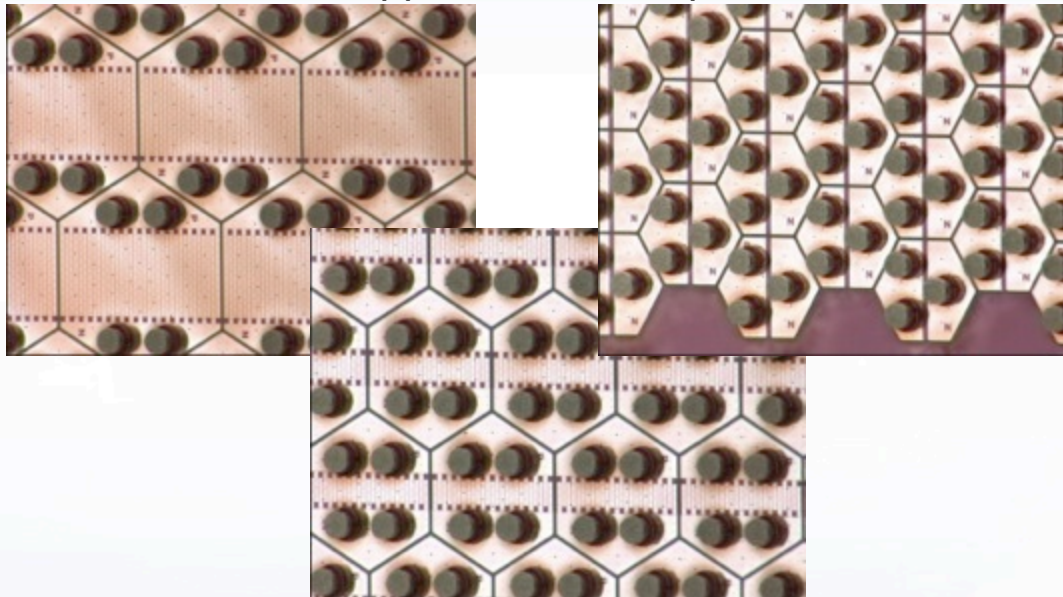
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Solar Cell Fabrication: Suspended Cells



Assembly

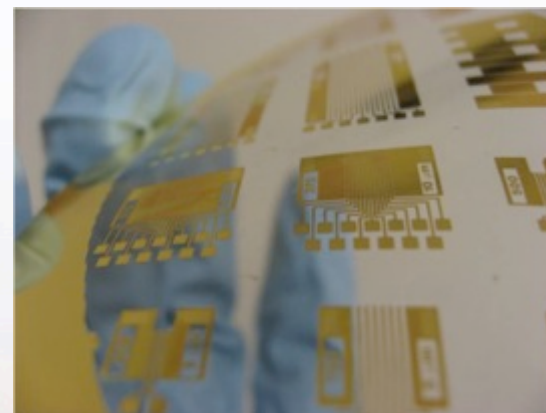
copper/solder bumps



flex receiver substrate (with cells)



pick-and-place (Universal Instruments)

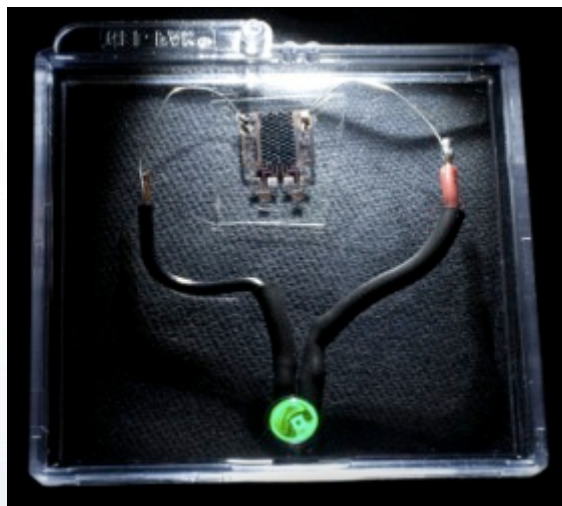


Corning® Willow™ Glass

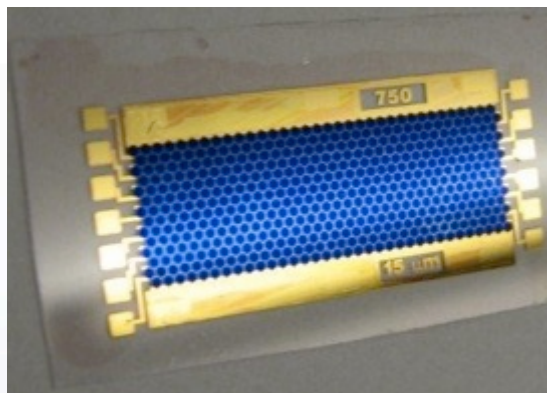


Prototype Examples

750um cell flexible prototypes on glass and polymer substrates



Corning® Willow™ Glass Substrate



Polymer Substrate



CORNING

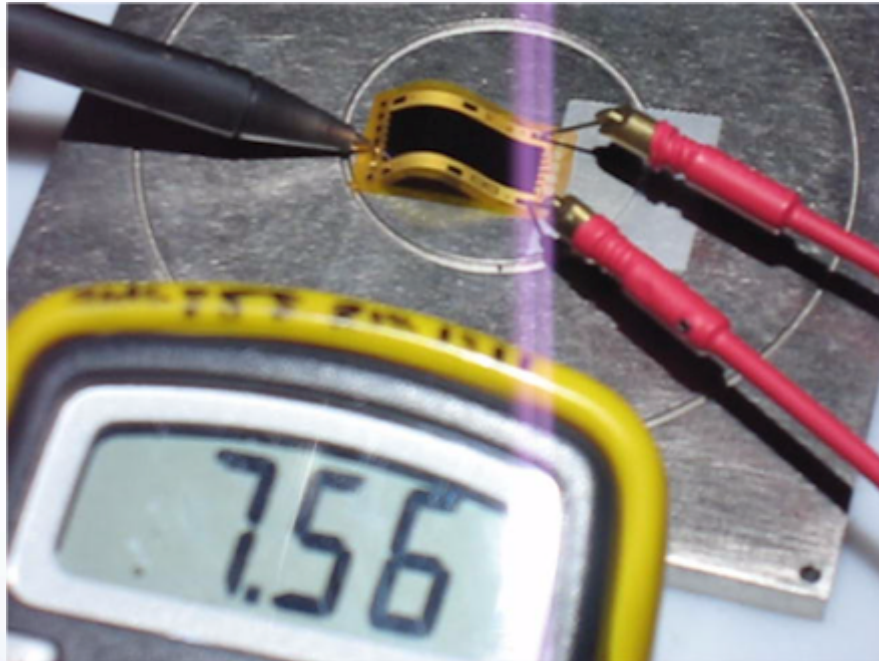


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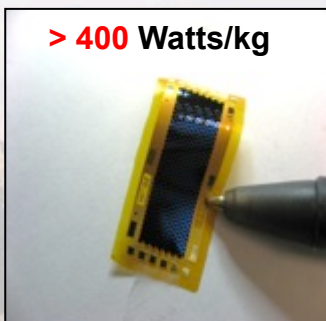
Prototype Examples

750um cell flexible prototype on polymer substrate

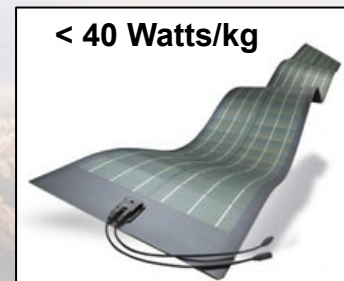
- Bend radius < 2mm without damage/ degradation.
- <100um as assembled.
- Demonstrated 14.9% array efficiency with single junction Si
 - >20% Si target
 - >35% multi-junction
- >1000 W/kg target (single junction).
- 10 kW array stowable into poster tube (“kW-in-a-can”).
- 10s of W in a pencil dimension tube.



MEPV



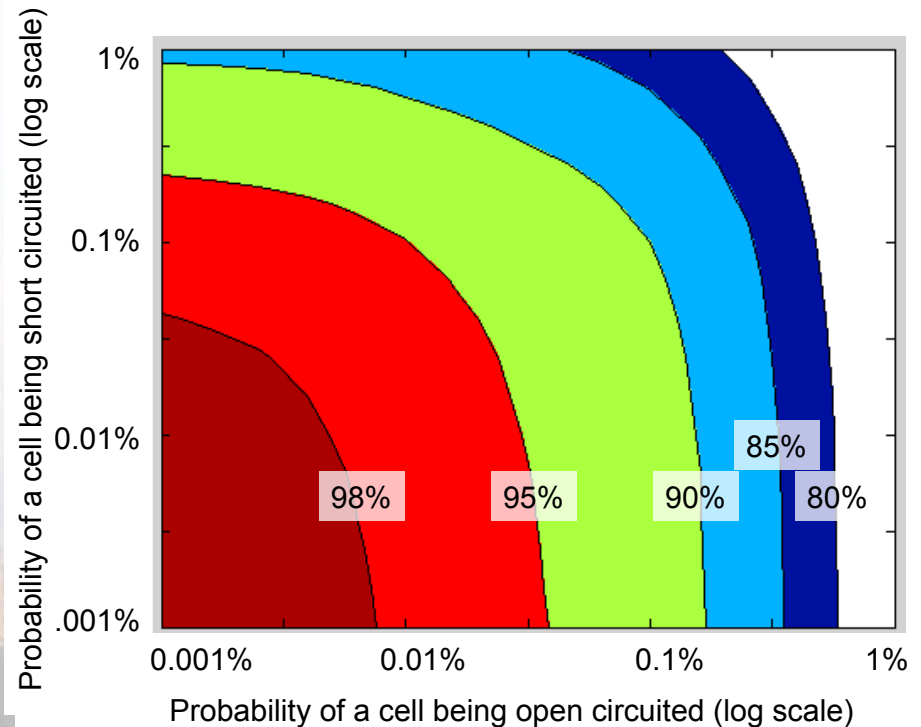
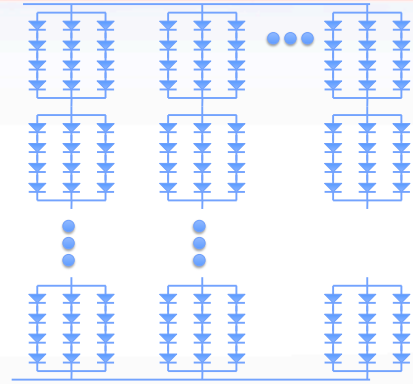
The Competition



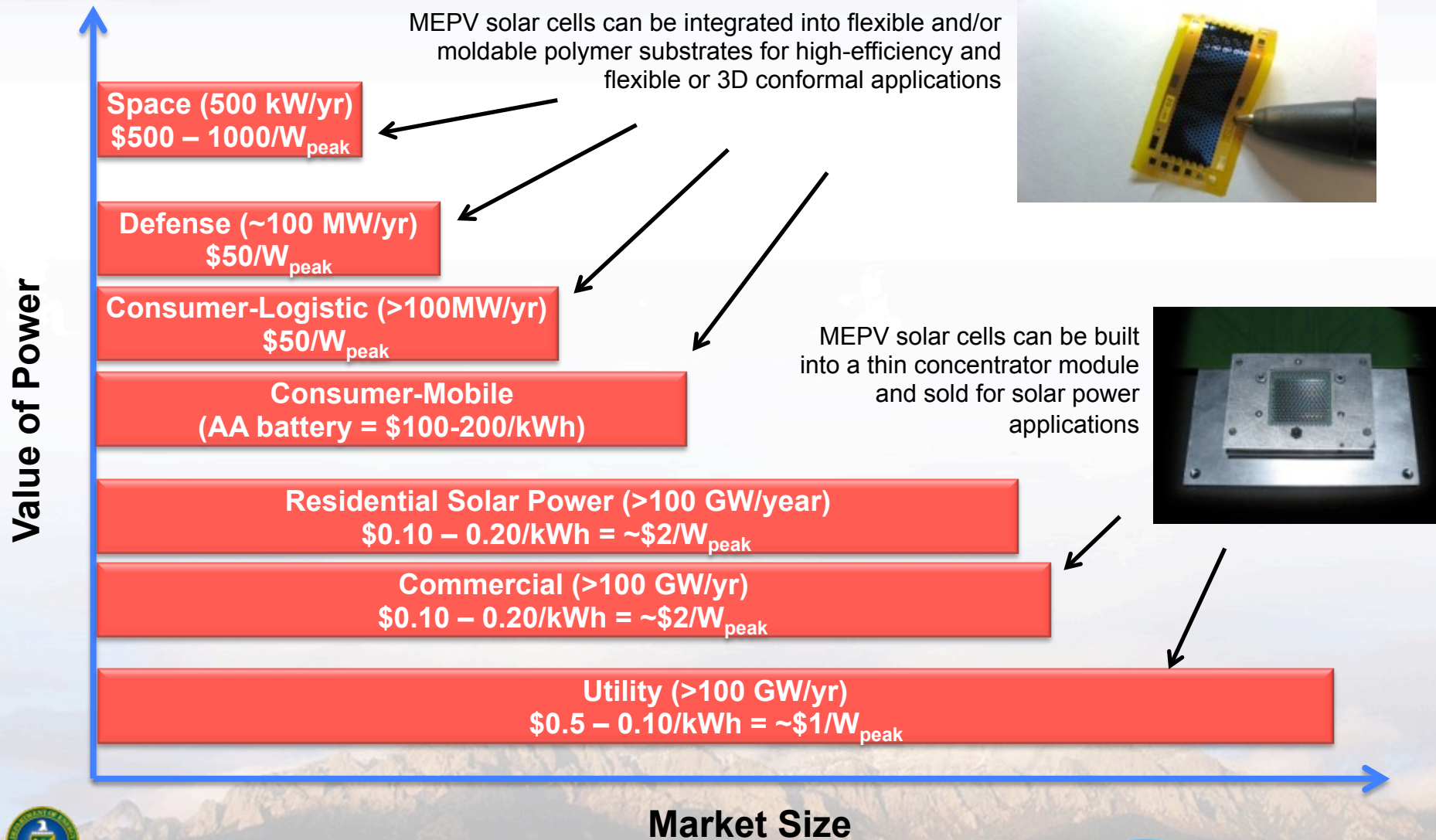
New Functionality

- Better performance in partial shading without the need for bypass protection diodes.
- Inherently robust (open/short, damage resistance).
- High-voltage DC (600 – 1000 V) in minimal footprint (5cm x 5cm).
- Integrated power management for on-the-fly optimization, voltage selection, state-of-health monitoring, logging.
- Reduced mechanical stresses and fatigue due to smaller cell/interconnect size.
- Integration of III-V layers/cells, independently connected junctions for highest performance possible.
- ...

With thousands of solar cells per square meter available, increasing levels of series-parallel-series-parallel connection networks of solar cells allow for improved performance (contour plot illustrates relative efficiency of module with different percentages of opens or shorts within the module).



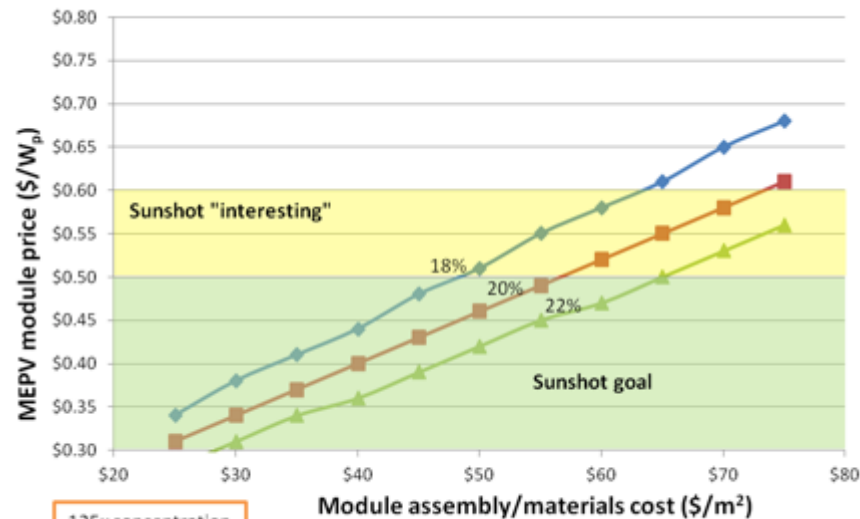
Broad Application: Power Markets



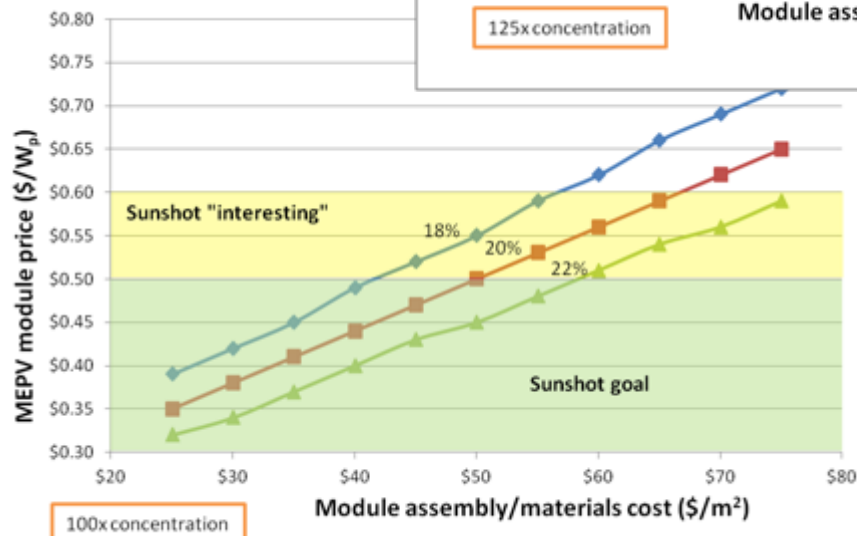
MEPV Cost Models

18% margin
200mm wafers

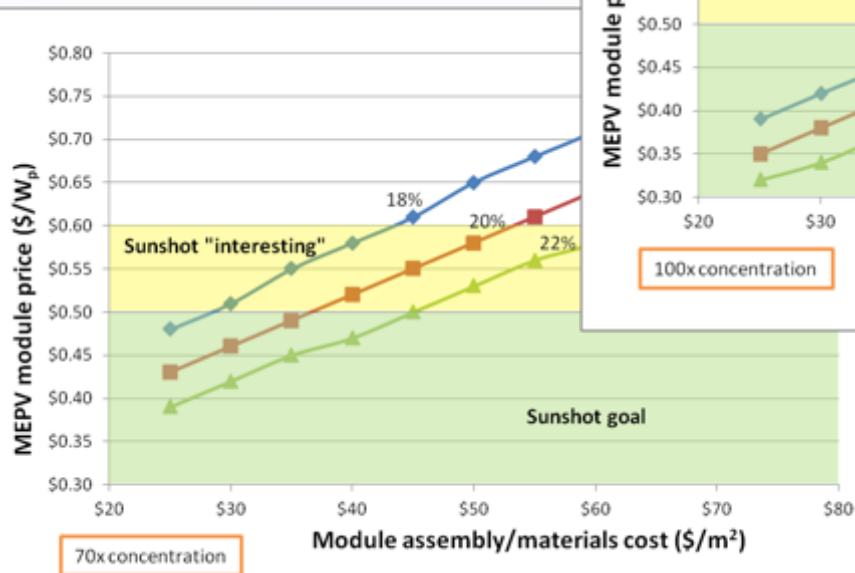
\$100/8" wafer
cell fab cost



125x



100x

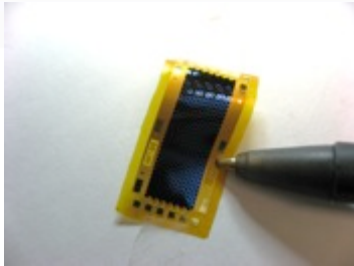


70x

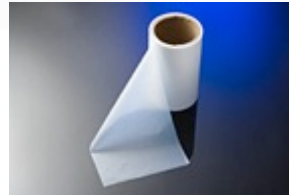
BOS costs are another \$0.50/W_p –
MEPV approach has the potential to
reduce those costs as well (integrated
power management, easier install, cheaper
trackers, etc.)

Where will we be in 2 years?

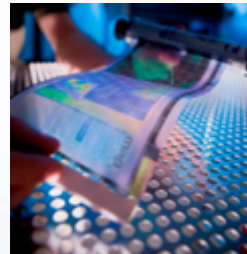
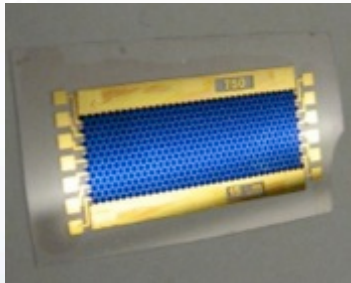
Now



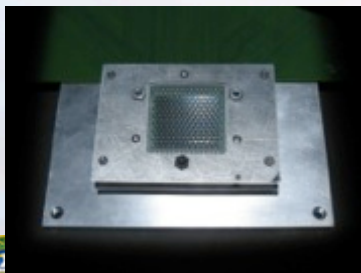
In 2 Years



Highly flexible prototype with
20% efficient, >1000 Watts/kg



Small prototype integrated system
for charging mobile devices



Low-Cost, High-Efficiency
MEPV concentrator prototype

Next Steps

Identify defense systems integrators, for high margin, differentiated applications of MEPV in a flexible format

Identify electronics manufacturers for partnering opportunities, focused on mobile charging/energy harvesting applications. Requires either flexible or conformal MEPV capabilities with high-efficiency.

Continue working with solar companies: both supply chain and system integrators



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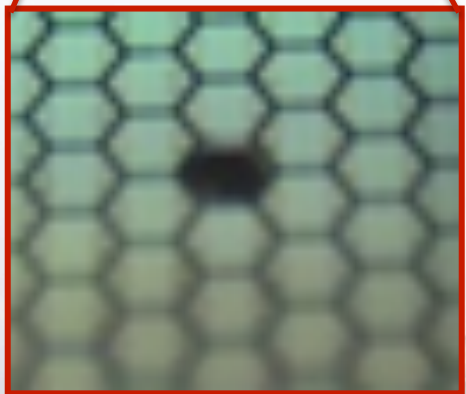
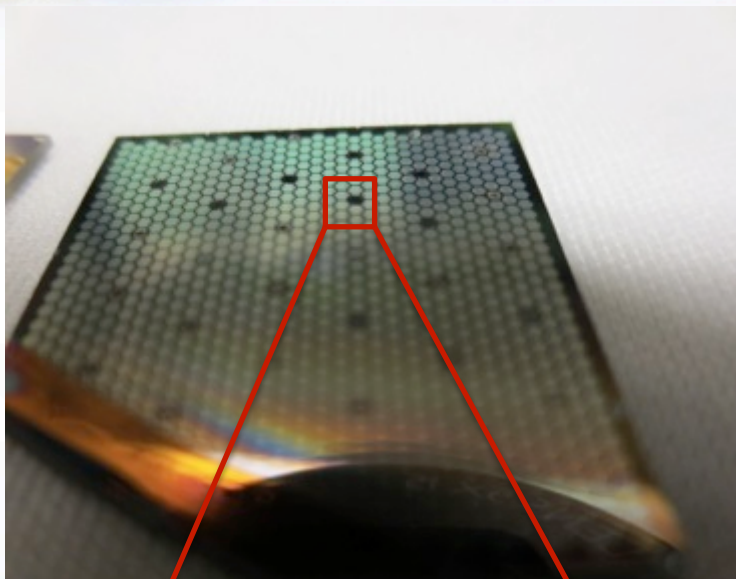


3DIC / Hybrid Integration

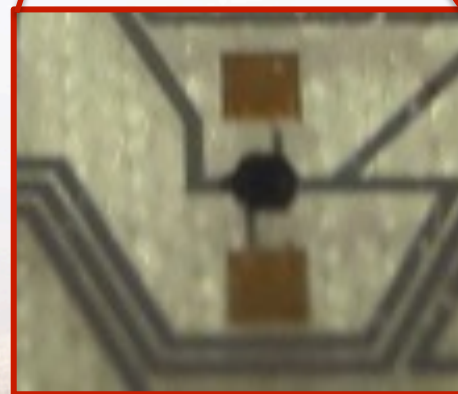
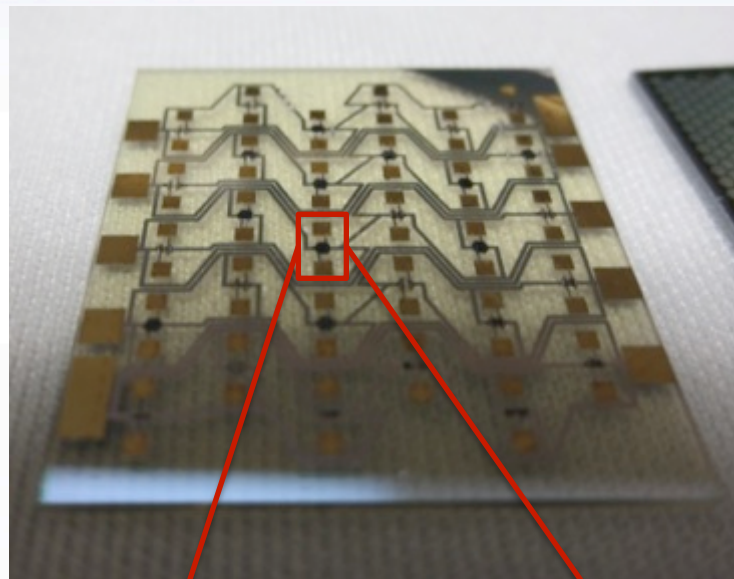
- Same technology base enables hybrid integration of dissimilar materials/processes with high throughput and high yield.
- Additional functionality integrated at chip or assembly level.
- Multiple assembly substrates possible.
- Current 3DIC approaches have significant issues with thin wafer handling, which is eliminated with this approach.



Sparse/Parallel Transfer



Donor Substrate with cells (ICs)



Receiver with cell transferred





Acknowledgements

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